

## 1-2600F/12



## Outline

- Fully-automatic wafer remounter that is designed to laminate a dicing tape to the opposite side of a wafer that is already mounted on a ring frame and dicing tape; then the original dicing tape is removed (transfer mount).
- A 6-jointed robot arm is used to cut the mounted tape before laminating the new tape, therefore, there is no adhesion between the two tapes.
- The tape cutting and wafer remounting process are all performed on the same

**Options** 

- Dicing Tape In-Line Pre-Cutting Host Communication Function(Communication Format: Conforms to
- SECS-I and HSMS/Software: Conforms to GEM)
   Vision System (Wafer ID Reader & Barcode Attachment System)
- OHT Compatible
   Ceiling FFU Installation

- Suitable Tape

  Dicing Tape: Adwill D Series, G Series
  Peeling tape for BG Tape: Adwill S Series

## Facility

**Power Supply** Voltage : AC200-230V±10%

(AC190-253V)

: 50/60Hz Frequency Phase : 3 phase Power consumption: 12kW

Air Supply Air pressure : 0.6-0.8MPa

> : <800L/min (ANR) Air consumption

Vacuum Supply Vacuum pressure : <-80kPa

Applicable Wafer Size 300mm (\*200 mm is optional)

Width(W): 3,323mm Size Depth(D) : 3,828mm

> Height(H): 2,227mm (excluding the signal tower and protruding parts)

Weight 3,700kg

UPH 30wafers/hour

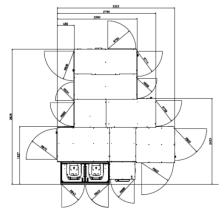
The above processing capacity is based on following conditions:

: 300mm non-polished mirror wafer Wafer

: D-675 from LINTEC Dicing tape

## External View

Unitmm







Top View Right Side View Front View



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